**Multilayer Ceramic Chip Capacitors** 

## C2012X7R2A103K085AA (TDK item description : C2012X7R2A103KT\*\*\*\*)

Applications		Commercial Grade
	Λ	Please refer to Part No. CGA4F2X7R2A103K085AA for automotive use.
Feature	Mid	Mid Voltage (100 to 630V)
Series C	C2012 [EIA CC0805]	



Size		
Length(L)	2.00mm +/-0.20mm	
Width(W)	1.25mm +/-0.20mm	
Thickness(T)	0.85mm +/-0.15mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.50mm Min.	
Recommended Land Pattern(PA)	1.00 to 1.30mm (Flow Soldering) 0.90 to 1.20mm (Flow Soldering)	Reflow Soldering)
Recommended Land Pattern(PB)	1.00 to 1.20mm (Flow Soldering) 0.70 to 0.90mm (Flow Soldering)	Reflow Soldering)
Recommended Land Pattern(PC)	0.80 to 1.10mm (Flow Soldering) 0.90 to 1.20mm (Flow Soldering)	Reflow Soldering)
Recommended Slit Pattern(SD)		

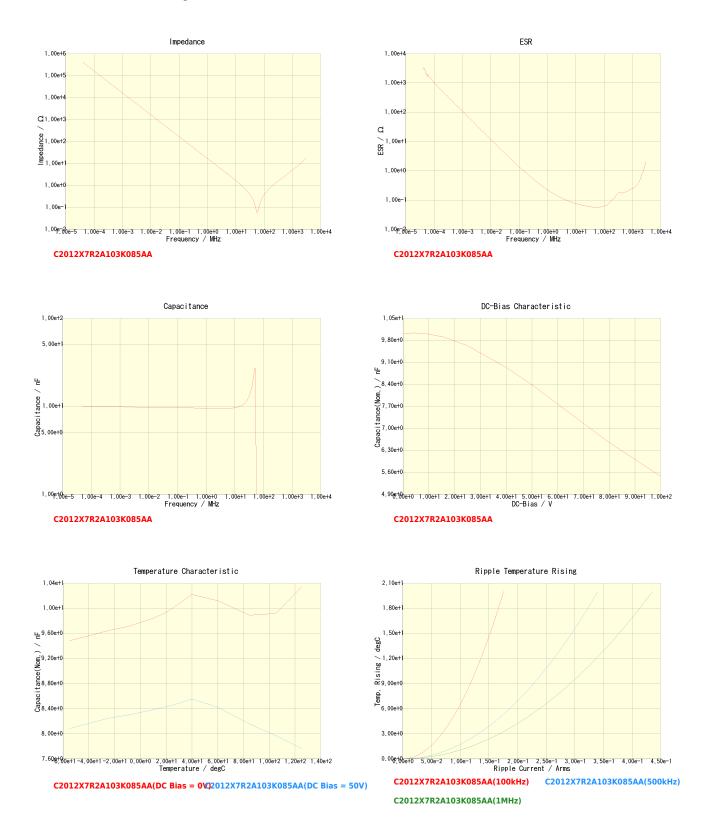
Electrical Characteristics				
Capacitance	10nF +/-10%			
Rated Voltage	100Vdc			
Temperature Characteristic	X7R(+/-15%)			
Dissipation Factor	3% Max.			
Insulation Resistance	10000MΩ Min.			

Other				
Soldering Method	Reflow, Flow			
AEC Q200	No			
Packing	Punched (Paper)Taping [180mm Reel]			
Package Quantity	4000Pcs Min.			

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Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



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